

ĐẠI HỌC QUỐC GIA TP.HỒ CHÍ MINH
TRƯỜNG ĐẠI HỌC BÁCH KHOA
KHOA ĐIỆN-ĐIỆN TỬ
BỘ MÔN KỸ THUẬT ĐIỆN TỬ



ASIC CHIP AND IP CORE DESIGN

Chapter 5: Physical Design

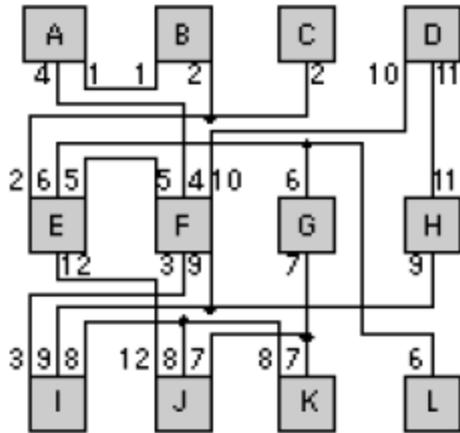
- 5.1 System partitioning
- 5.2 Floorplanning and placement
- 5.3 Routing

5.1 System Partitioning

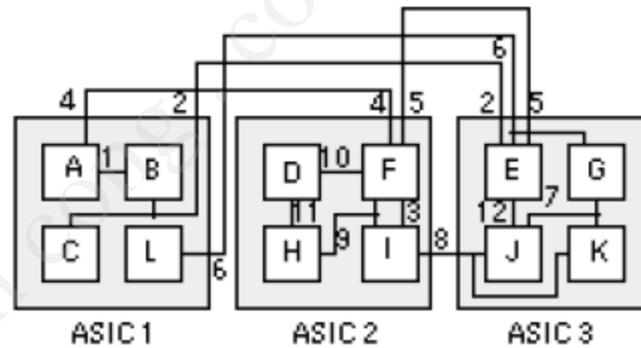
- System partitioning requires goal and objectives
 - A maximum size of each ASIC
 - A maximum number of ASICs
 - A maximum number of connections for each ASIC
 - A maximum number of total connections between all ASICs
- Example
 - Use no more than 3 ASICs
 - Each ASIC contains no more than 4 logic cells
 - Use the minimum number of external connections for each ASIC
 - Use the minimum total number of external connections

Partitioning Example

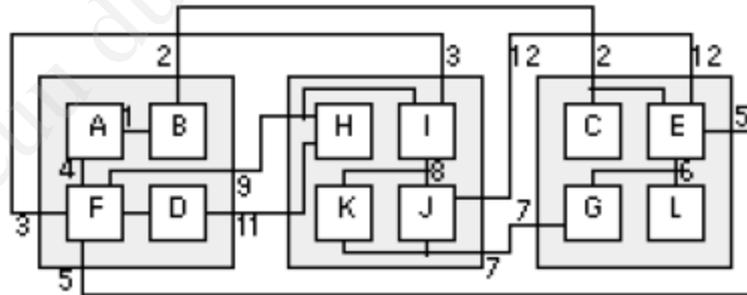
- Example



A design to be partitioned



A partitioning with 5 connections
(nets 2, 4, 5, 6, 8)



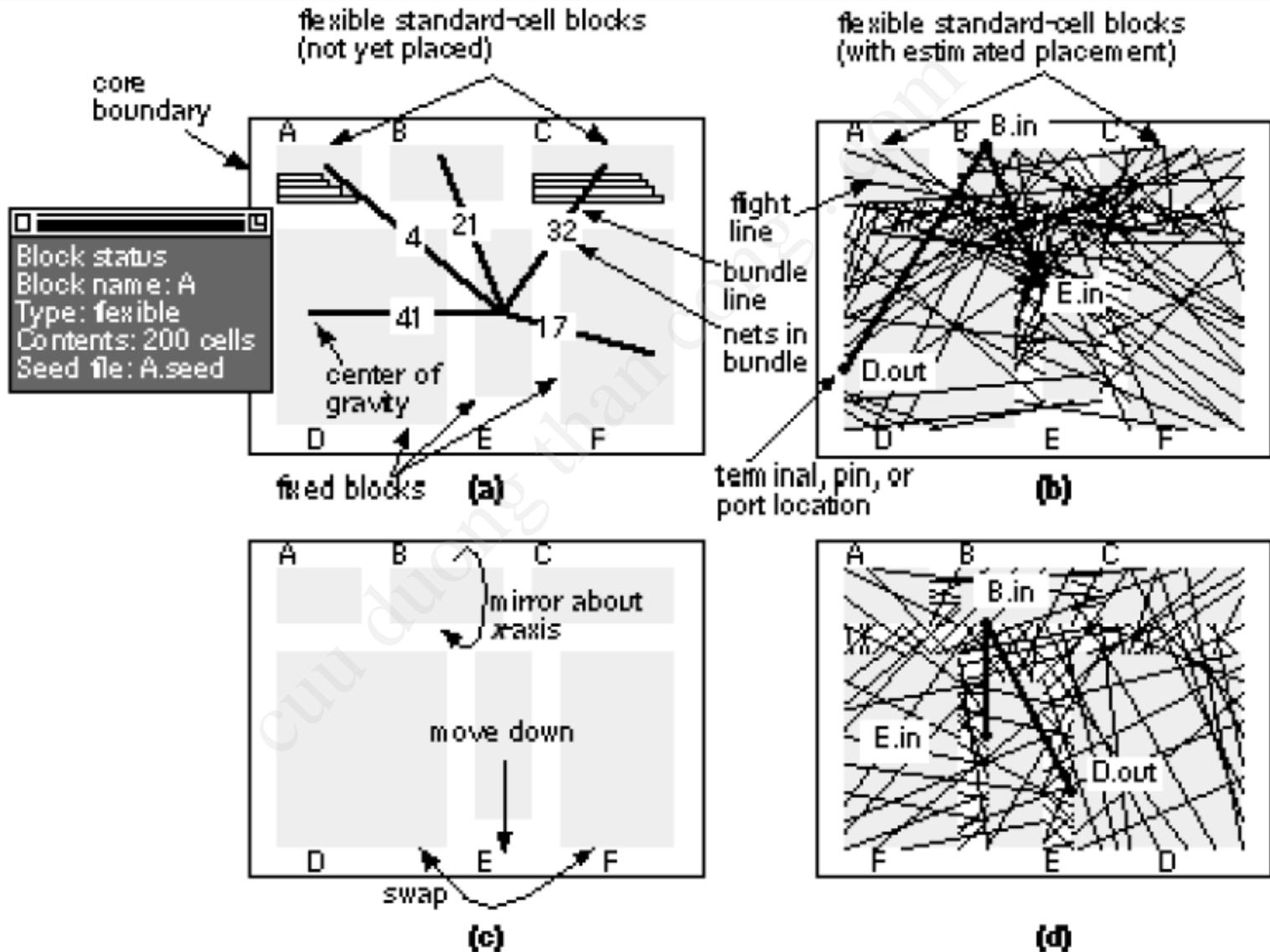
A constructed partitioning using logic cell C as a seed



5.2 Floorplanning and Placement

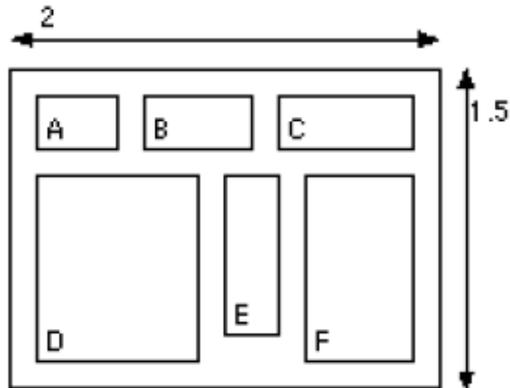
- Floorplanning:
 - Goals:
 - Arrange the blocks on a chip
 - Decide the location of the IO pads
 - Decide the location and number of the power pads
 - Decide the location and type of clock distribution
 - Objectives:
 - Minimize the chip area
 - Minimize delay

Floorplanning Examples



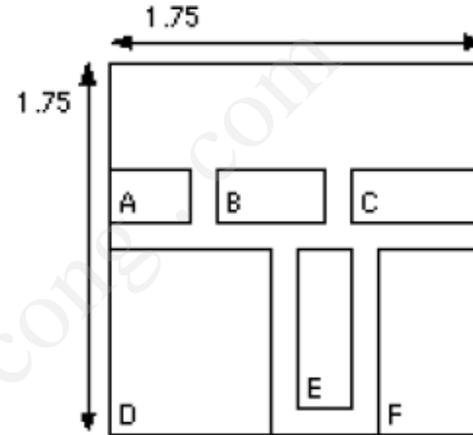
Floorplanning Examples

Initial floorplanning with 2:1.5 ratio



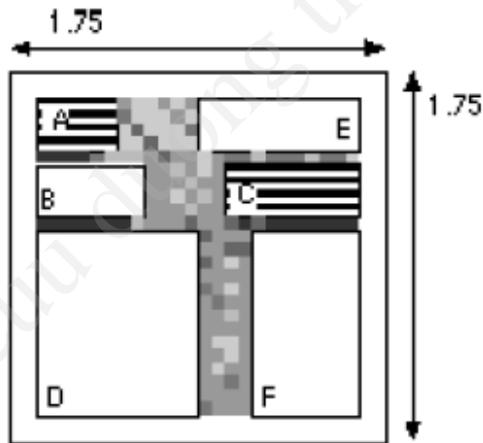
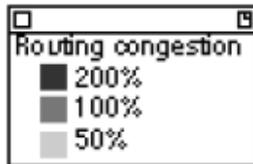
(a)

Floorplanning with 1:1 ratio



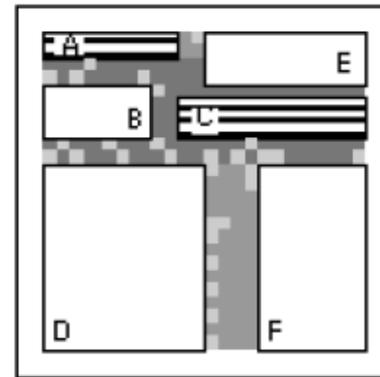
(b)

A trial floorplanning



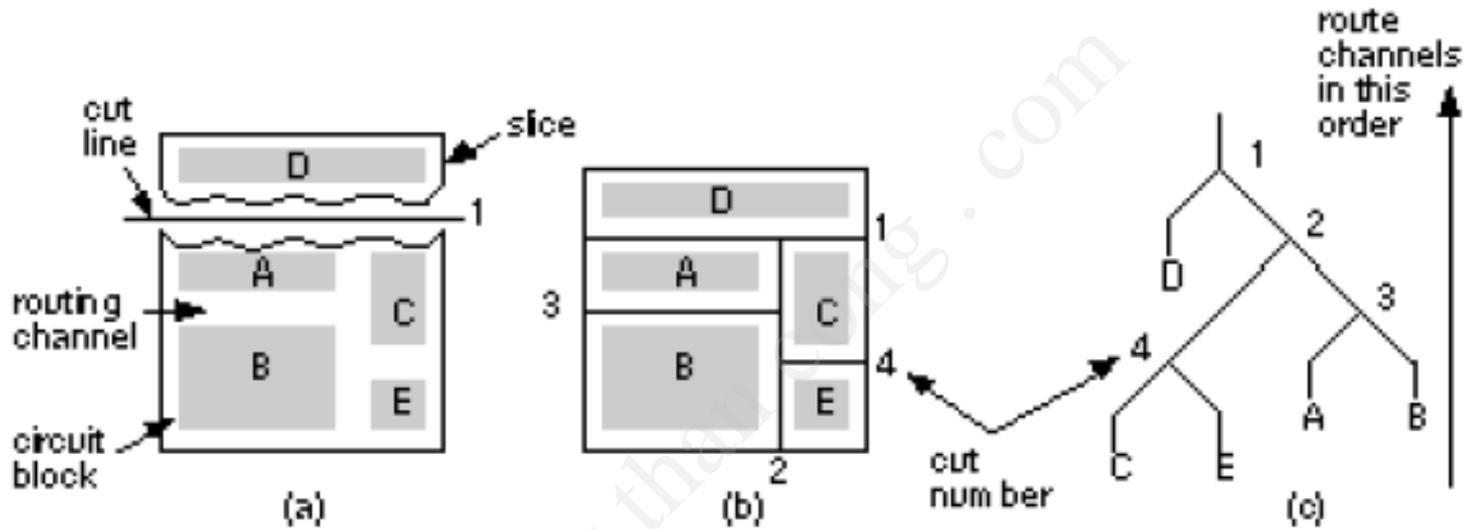
(c)

Resizing block A and C



(d)

Define Channel Routing Order

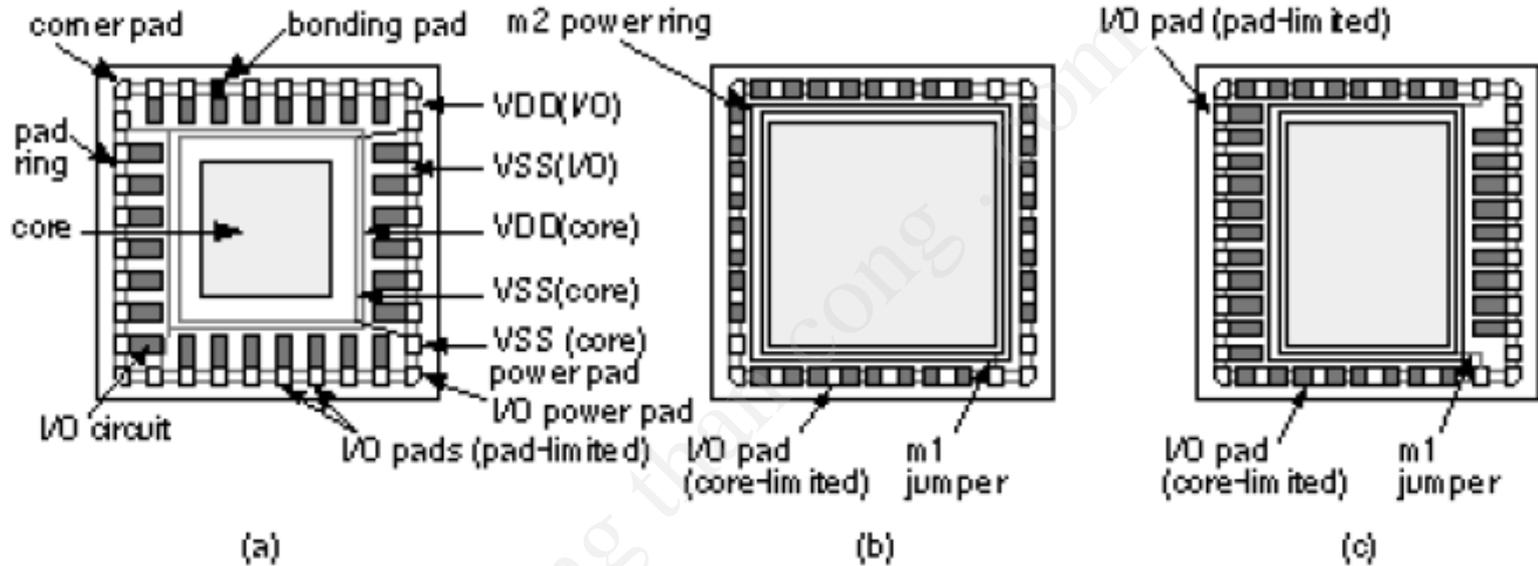


Make a cut for the first routing

A sequence of cuts

A slicing tree

IO and Power Planning



A pad-limited die
(The number of pads
determines the die size)

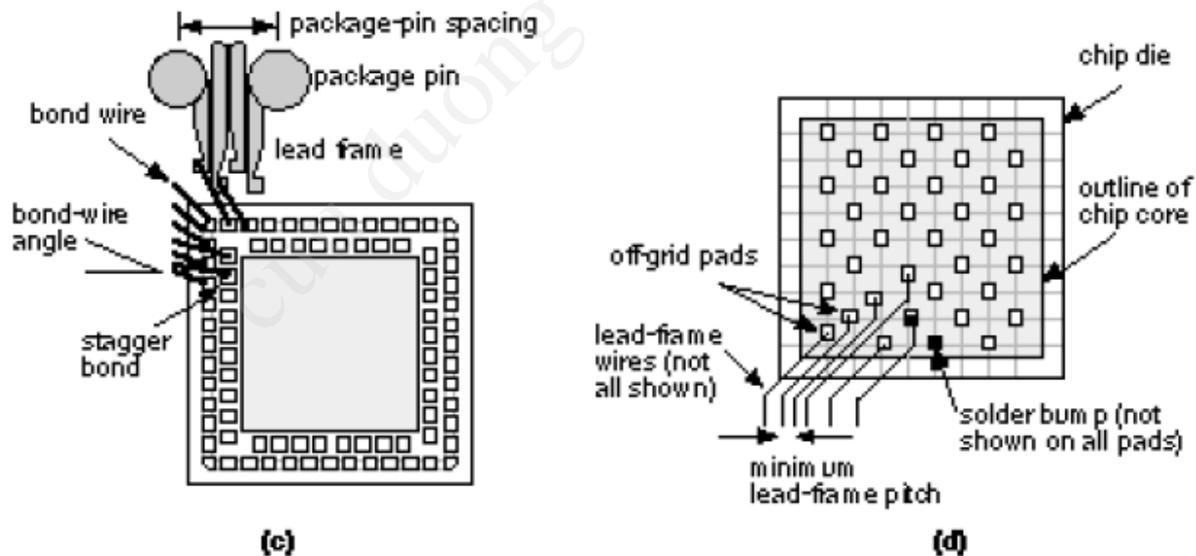
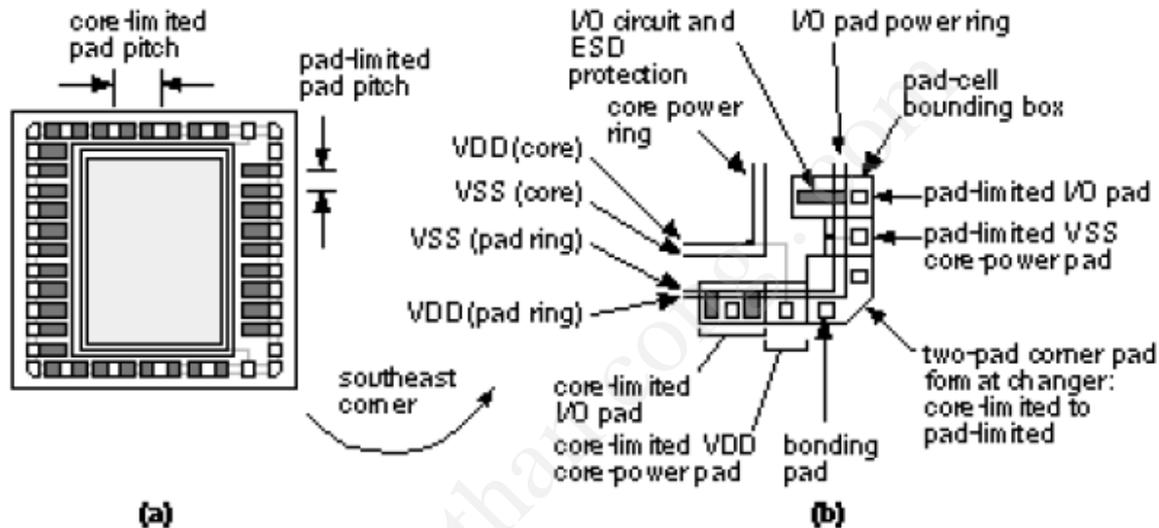
=> Use tall, thin pads

A core-limited die
(The core logic
determines the die size)

=> Use short, wide pads

Using both pad-limited
pads and core-limited
pads for square die

Bonding Pads



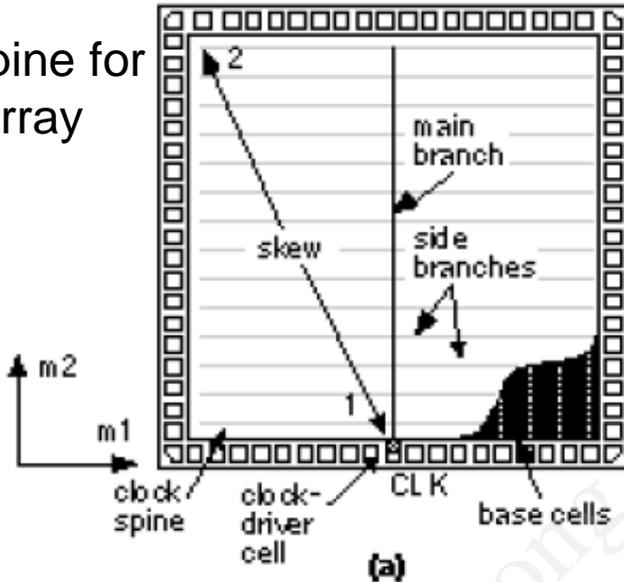


Floorplanning Process

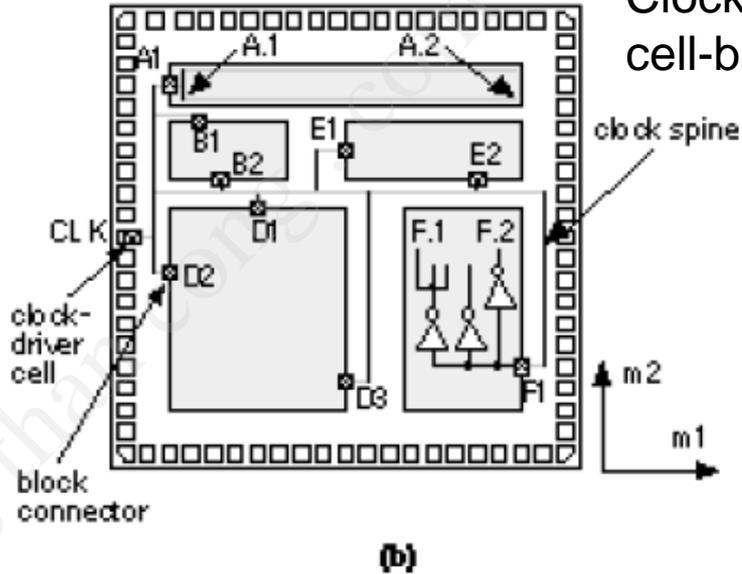
- Define and create core area
- Create/assign IO pin
- Place pins or IO pads
- Make connect pins, standard cell
- Create power ring, strap, grid
- Check floorplanning

Clock Planning

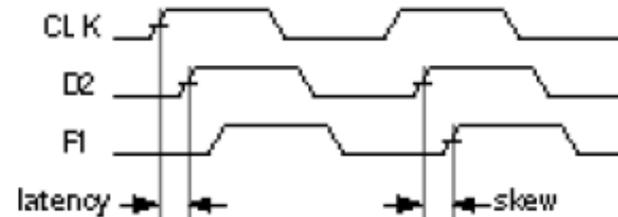
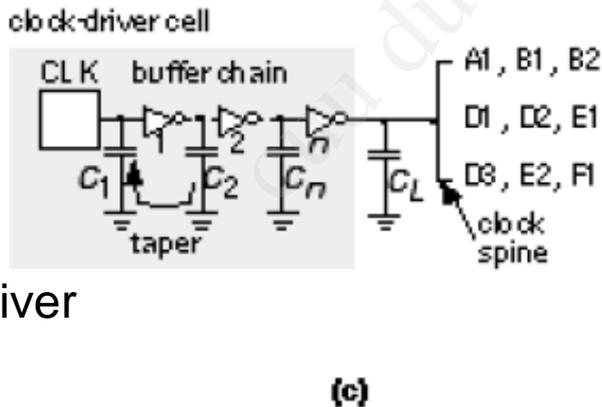
Clock spine for a gate array



Clock spine for a cell-based ASIC



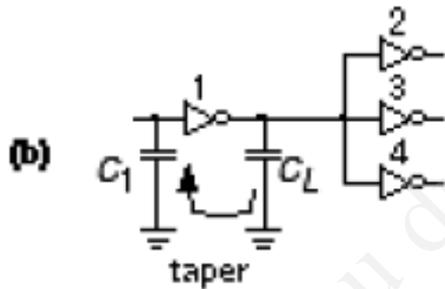
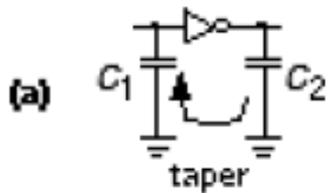
Delay in driver cell



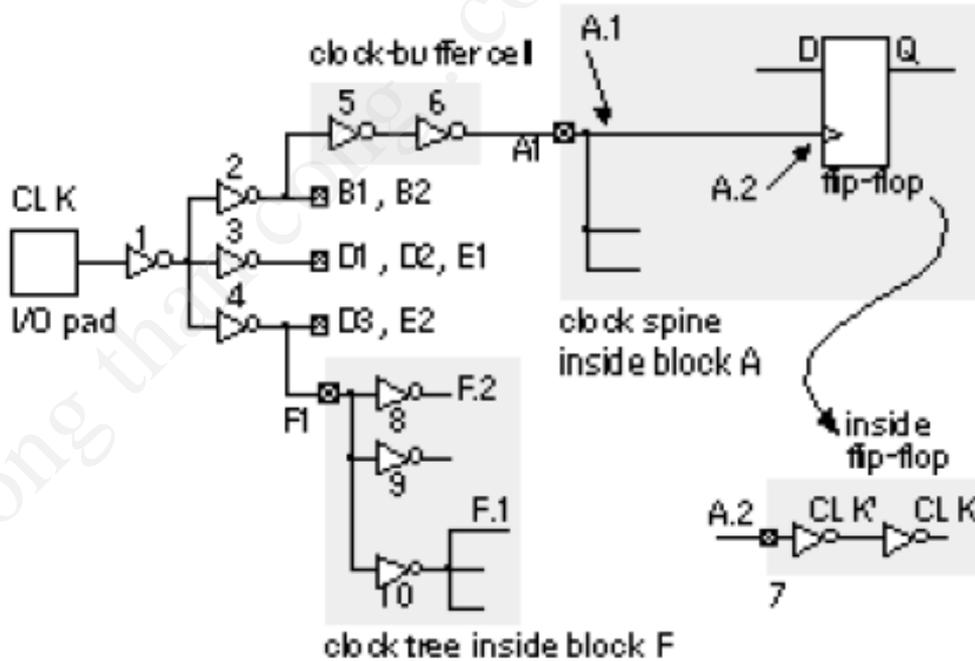
Clock latency and Clock skew

Clock Tree

Minimum delay



Using a fanout of the three at successive nodes



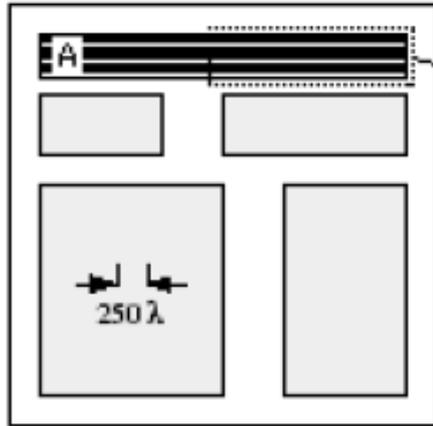
Clock tree for the cell-based ASIC



Placement

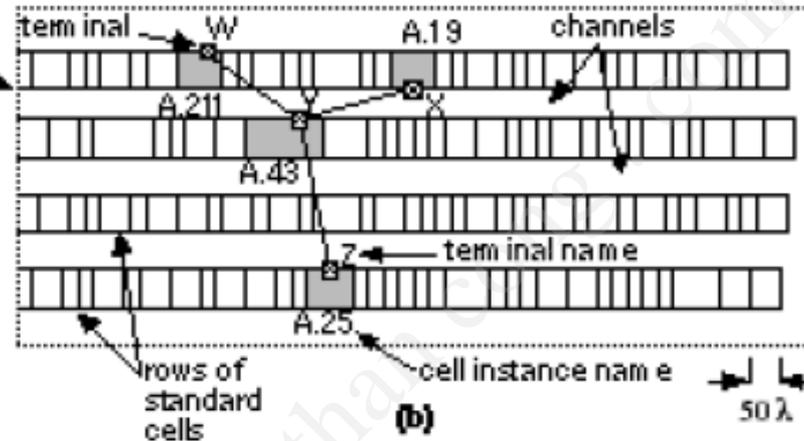
- Objectives
 - Guarantee the router can complete the routing step
 - Minimize all the critical net delays
 - Make the chip as dense as possible
 - Minimize power dissipation
 - Minimize cross talk between signals

Placement Example



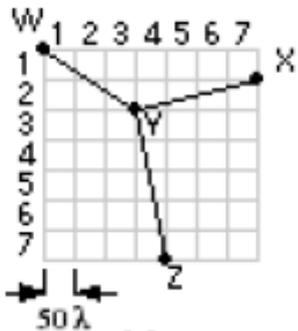
(a)

expanded view of part of flexible block A



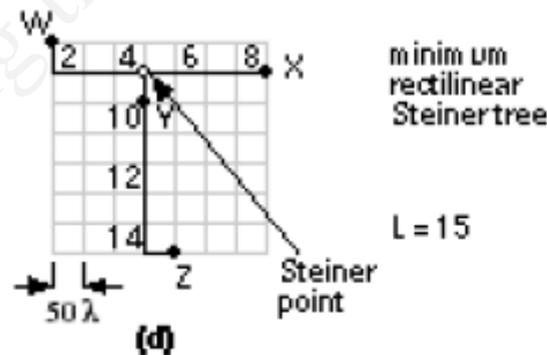
(b)

Four rows of standard cells



(c)

L = 16



(d)

minimum rectilinear Steiner tree

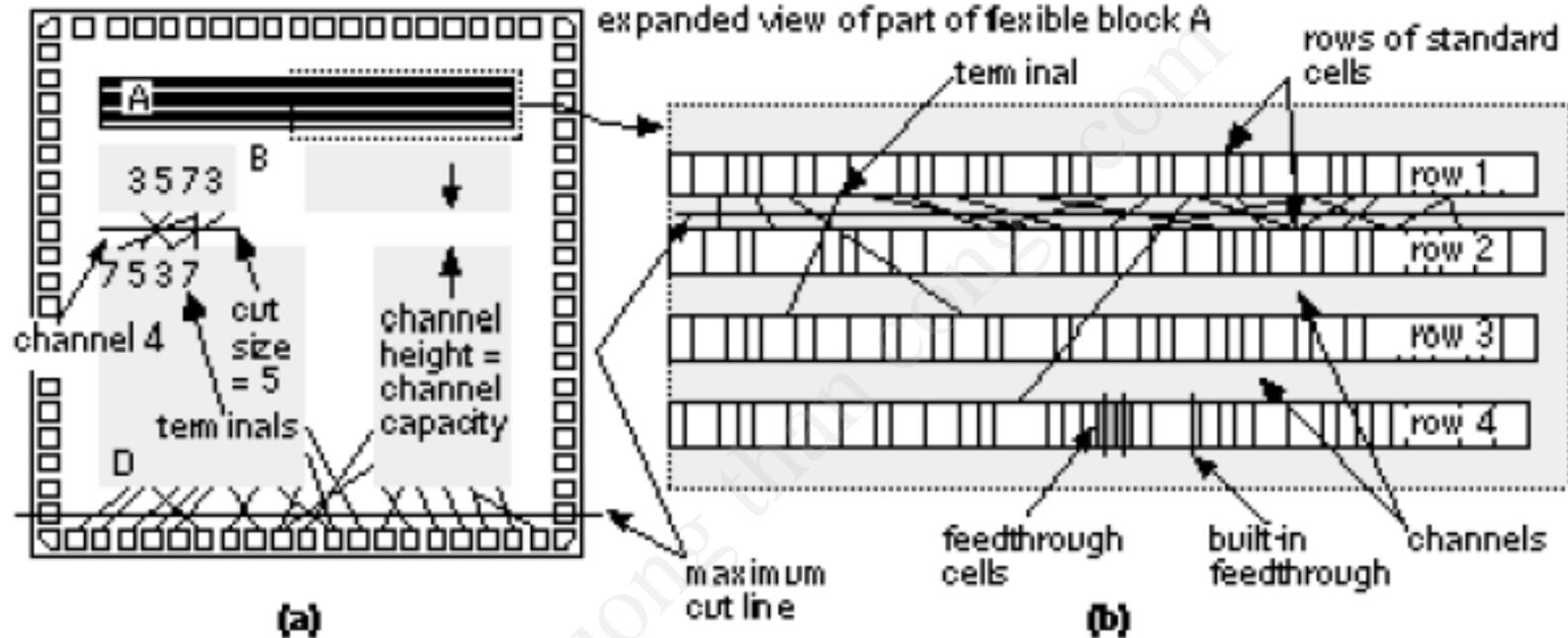
L = 15

Steiner point

The problem for the net (W, X, Y, Z)

The minimum rectilinear Steiner tree using Manhattan routing

Measurement of Congestion



Measurement of congestion

A expanded view of flexible block A



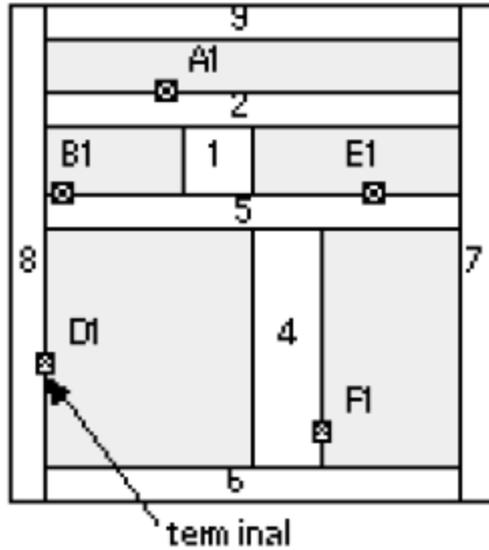
Placement Process

- Setup placement options
- Auto place
- Congestion-Driven
- Timing-Driven
- Analyze congestion
- Analyze timing

5.3 Routing

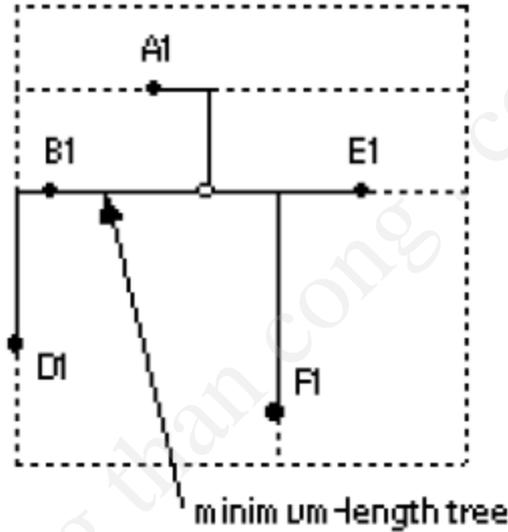
- **Global Routing:** determines the channels to be used for each interconnect
 - Minimize the total interconnect length
 - Maximize the probability that the detailed router can complete the routing
 - Minimize the critical path delay
- **Detail Routing:** decides the exact location and layers for each interconnect
 - Minimize the total interconnect length and area
 - Minimize the number of layers changes that the connections have to make
 - Minimize the delay of critical paths

Global Routing Between Blocks



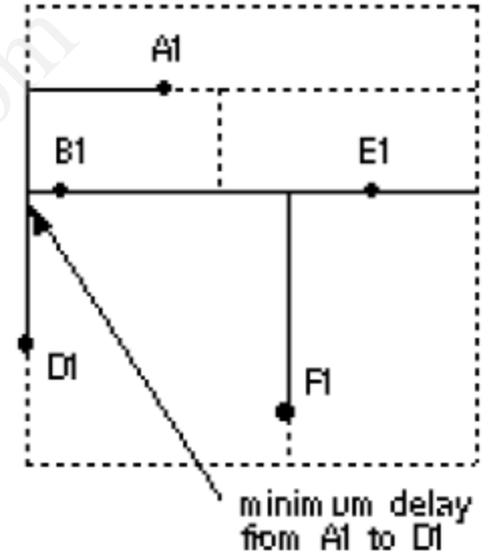
(a)

A cell-based ASIC showing a single net with a fanout of four



(b)

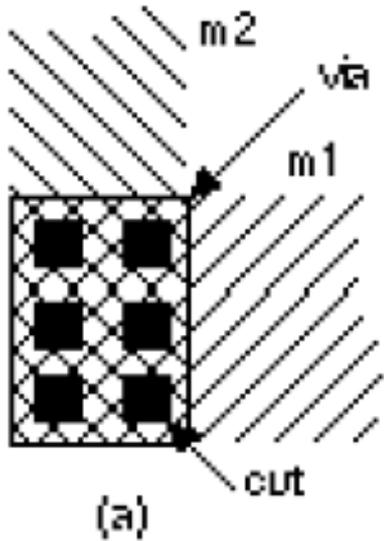
Terminals are projected to center of the nearest channel



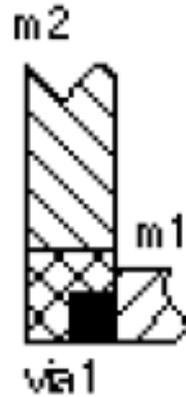
(c)

The minimum-length tree

Via and Contact in Detail Routing



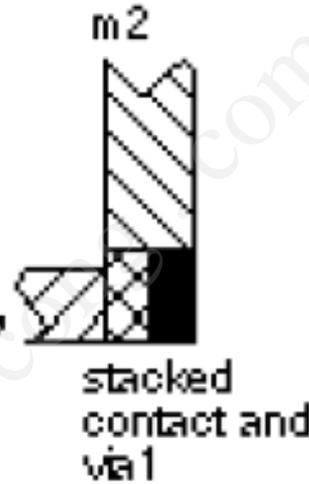
(a) A large via



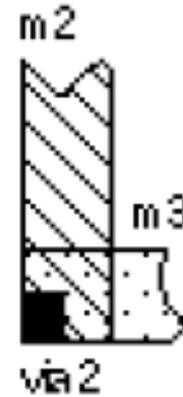
(b) A via 1



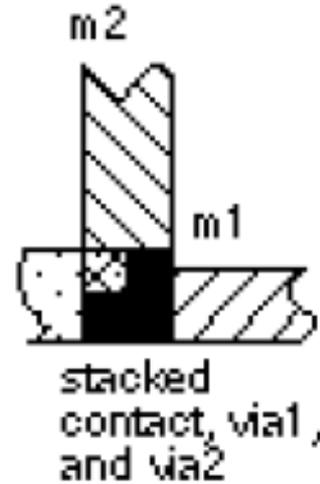
(c) A contact from m1



(d) A via 1 placed over a contact



(e) A via 2



(f) A via 2 stacked over a via 1



Routing Process

- Setup up for routing
- Global route, track assign, detail route
- Route clock
- Route signal
- Optimize post route
- Report timing
- Report DRC/LVS

Physical Design Tools

- Floorplanning/placement/routing tools:
 - Design compiler:
 - IC Compiler: for netlist-to-GDSII
 - IC Compiler-XP: for the process 130nm and above
 - IC Compiler-PC: for netlist-to-clock-tree-synthesis
 - IC Compiler-DP: for design planning
- Timing analysis tool
 - Prime Time
 - Post-layout timing verification

IC Design Compiler Flow

